



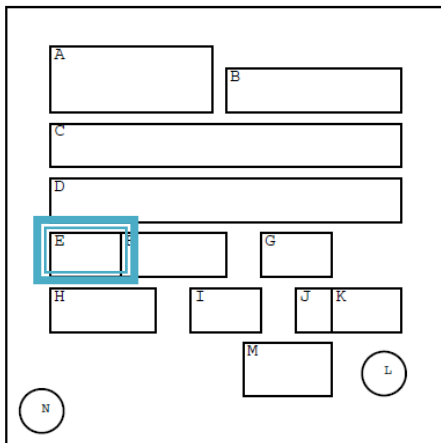
PRODUCT/PROCESS CHANGE NOTIFICATION PCN 9975 – Additional information

Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in BGA package

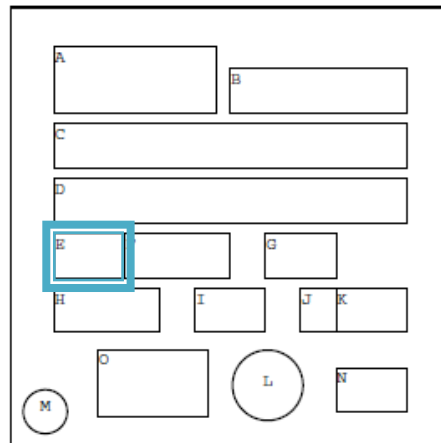
MDG - Microcontrollers Division (MCD)

How can the change be seen?

For LFBGA 10x10x1.7 100 package, the marking instruction of the assembly plant indicated on the products is changing from GH (in E) to GQ (in E).

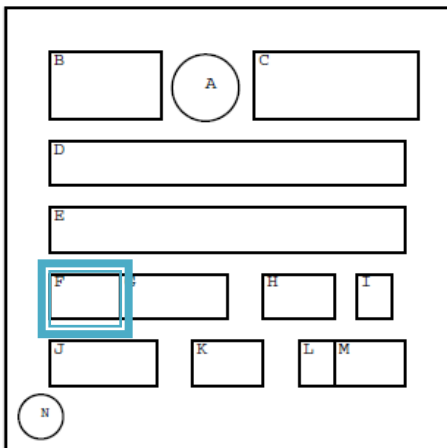


Example of previous marking

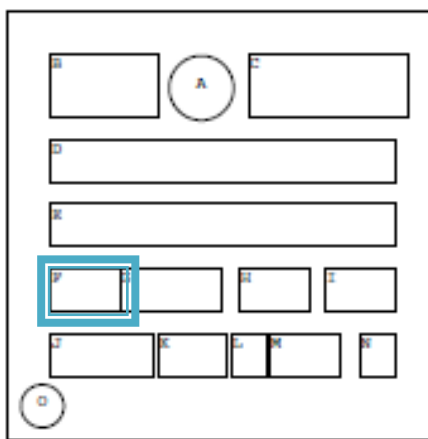


Example of new marking

For LFBGA 10x10x1.7 144 package, the marking instruction of the assembly plant indicated on the products is changing from GH (in F) to GQ (in F).



Example of previous marking



Example of new marking

How to order samples?

For all sample request linked to this PCN, please:

- request sample(s) through Notice tool, indicating a single Commercial Product for each request.
- insert "PCN 9975" into the remarks of your order.
- place **non standard** sample order using the following field in your system.

SO | NPO Sample

Header

SO Nr: [] Customer: [] SO Type: 38 Sample Order

PO Nr: [] Carrier Code: [] Price Policy: [] Currency: []

Notes: [] States: [] Issuing Date: [] Ord Val: 0.0000

Sch 1 Nr	PO 1 Nr	Finished Good	Comm Qty	Open Qty	Plant Open Qty	Reqd Qty	Unit Price	RD	CD	EDD	St

PO Item: [] Comm Prod: [] Qty: 0 RD: 06-Jan-15 Unit Price: 0.0000 Final Cost: []

Cust Part Nr: [] Finishd Good: [] Partial Ship: 01 Price Pol: [] Status: 01 Conc: []

Notes: [] TAM K Pieces: 0 Our Share%: 0 Sample Type: **Sample Non Std Type**

Project Name: [] Closing Date: [] Closing Type: []

Regional Sheet: [] Lab Sheet: []

SO Nr: 7075S05890 Customer: 99800200 SGS-TH/USA PO Nr: Mos/TPapay/RBC-Ullmer

Company: STM Issuing Date: 29-JUL-2015 12:07:00 Ship To: 9980020081 SGS/USANPO Price Policy: 05 Curr Code: 02 U.S. DOLLAR

Carrier Code: 0001 * Bill To: 9980020001 SGS-TH/USA

Carriage Code: F1 F.I.S. Confirm To: 81

Transportn Mode: 01 AIR FREIGHT Sales Rep. ID: 07R000 NO COMMISSION

Payment Term: 0006 FREE OF CHARGE Cust Serv Rep ID: 11A000 Dummy FSA SWISS

SO Remark Details

SO Nr: 7075S05890

SO Remark Type	Text	atus Co	Last Upda
01 INVOICE & O/C REMARK	PER PCN 9108- THANK YOU	01	30-Jul-2015



PCN 9975 - MCDRER1624

Qualification Plan LFBGA10x10

Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC)

Dec 13th 2016

MDG MCD Quality & Reliability Department

PCN 9975- MCDRER1624 Qualification Plan JSCC plant for LFBGA10x10 package

- Qualification plan for changes described in the PCN 9975
- Reliability report: RERMCD1624
- Test Vehicles

Package line	Package	Device (Partial RawLine Code)	Diffusion Process	Number of qual Lots
LFBGA 10x10	144b	STR7 (X3*401)	M8T	1
	144b	STM32 (X3*430)	TSMC 0.18μm	1
	100b	STM32 (H0*414)	TSMC 0.18μm	1

Package Reliability Trials :

(*) tests performed after preconditioning

PCN 9975- RERMCD1624

JSCC LFBGA10x10 RELIABILITY TRIALS

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Reliability Trial	Test Conditions	Pass Criteria	Unit per Lot	Lot qty	
PC	Pre Conditioning: Moisture Sensitivity Jedec Level 3 J-STD-020/ JESD22-A113	Bake (125°C / 24 hrs) Soak (30°C / 60% RH / 192 hrs) for level 3 Convection reflow: 3 passes	3 passes MSL3	308	1/ device qual
AC or Uhast(*)	Autoclave JESD22 A102 or UnBiased Highly Accelerated Temperature and Humidity Stress JESD22 A118	121°C, 100% RH, 2 Atm 130°C, 85%RH, 2 atm	96h	77	1/ device qual
TC(*)	Thermal Cycling JESD22 A104	-50°C, +150°C Or equivalent -65°C +150°C	1000Cy 500Cy (1000cy/2000cy as monitoring)	77	1/ device qual
WPT/WBS After TC	Wire Bond Pull- Mil Std883 method 2011 Wire Bond Shear ,AECQ100-001	3g min pull strength 15g min bond shear	500Cy 1000Cy 2000Cy		
THB(*) or HAST(*)	Temperature Humidity Bias JESD22 A101 Biased Highly Accelerated temperature & humidity stress JESD22 A110	85°C, 85% RH, bias 110°C, 1.2 atm , 85% RH bias	1000h 264h	77 77	1/ device qual
HTSL	High Temperature Storage Life JESD22 A103	150°C- no bias	1000h	77	1/ device qual
Construction analysis including Solderability, Physical demensions	JESD 22B102 JESDB100/B108			15 10	1/ Lead frame and Front end technology
ESD	ESD Charge Device Model ANSI/ESD STM5.3.1	250V / 500V/ 750V depending on device datasheet	250V or 500V or 750V	3	1/ device qual

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Public Products List

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PCN Title : Transfer assembly plant from Stats ChipPAC Shanghai China (SCC) to Stats ChipPAC Jiangyin China (JSCC) for products in BGA package

PCN Reference : MDG/17/9975

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

STM32F103ZGH6JTR	STM32F103VCH6	STM32F103VBH6
STM32F103VEH6	STM32F103ZGH6TR	STM32F107VCH6
STM32F103VEH6TR	STM32F103VEH7	STM32F103ZEH6TR
STM32F103VDH6TR	STM32F103ZEH6	STM32F103ZGH6J
STM32F103ZFH6	STM32F103ZCH6	STM32F103ZGH6
STM32F103ZEH7	STR710RZH6	STM32F103ZFH6TR
STR710FZ2H6	STM32F103VBH7	STM32F103V8H6
STM32F103ZDH6	STR710FZ1H6	STM32F103ZGH7
STM32F103VDH6	STM32F103ZDH6TR	STM32F105VBH6



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